#### **Features**

- 3.0V to 5.5V Operation
- Industry Standard Architecture
  - Emulates Many 20-Pin PALs<sup>®</sup>
  - Low Cost Easy-to-Use Software Tools
- High Speed
  - 10 ns Maximum Pin-to-Pin Delay
- Ultra-Low Power
  - 5 μA (Max.) Pin-Controlled Power Down Mode Option
  - Typical 100 nA Standby
- CMOS and TTL Compatible Inputs and Outputs
  - I/O Pin Keeper Circuits
- Advanced Flash Technology
  - Reprogrammable
  - 100% Tested
- High Reliability CMOS Process
  - 20 Year Data Retention
  - 100 Erase/Write Cycles
  - 2,000V ESD Protection
  - 200 mA Latchup Immunity
- Commercial and Industrial Temperature Ranges
- Dual-in-Line and Surface Mount Packages in Standard Pinouts

#### **Description**

The ATF16LV8C is a high-performance EECMOS Programmable Logic Device that utilizes Atmel's proven electrically erasable Flash memory technology. Speeds down to 10 ns and a 5  $\mu$ A pin-controlled power down mode option are offered. All speed ranges are specified over the full 3.0V to 5.25V range for industrial and commercial temperature ranges.

(continued)

High-

**EE PLD** 

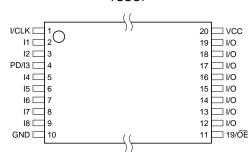
**Performance** 

ATF16LV8C

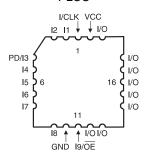
### **Pin Configurations**

Pin Name	Function
CLK	Clock
1	Logic Inputs
I/O	Bidirectional Buffers
OE	Output Enable
VCC	(+3V to 5.5V) Supply
PD	Programmable Power Down Option



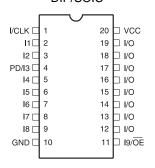


#### PLCC



Top View

DIP/SOIC







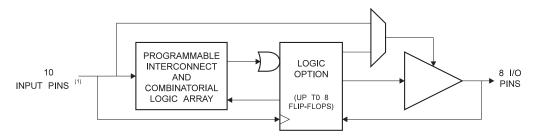


The ATF16LV8C incorporates a superset of the generic architectures, which allows direct replacement of the 16R8 family and most 20-pin combinatorial PLDs. Eight outputs are each allocated eight product terms. Three different modes of operation, configured automatically with software, allow highly complex logic functions to be realized.

The ATF16LV8C can significantly reduce total system power, thereby enhancing system reliability and reducing

power supply costs. When pin 4 is configured as the power down control pin, supply current drops to less than 5  $\mu A$  whenever the pin is high. If the power down feature isn't required for a particular application, pin 4 may be used as a logic input. Also, the pin keeper circuits eliminate the need for internal pull-up resistors along with their attendant power consumption.

#### **Block Diagram**



Note: 1. Includes optional PD control pin.

#### **Absolute Maximum Ratings\***

Temperature Under Bias40°C to +85°C
Storage Temperature65°C to +150°C
Voltage on Any Pin with Respect to Ground2.0V to +7.0V <sup>(1)</sup>
Voltage on Input Pins with Respect to Ground During Programming2.0V to +14.0V <sup>(1)</sup>
Programming Voltage with Respect to Ground2.0V to +14.0V <sup>(1)</sup>

\*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note:

Minimum voltage is -0.6V dc, which may undershoot to -2.0V for pulses of less than 20 ns. Maximum output pin voltage is Vcc + 0.75V dc, which may overshoot to 7.0V for pulses of less than 20 ns.

#### **DC and AC Operating Conditions**

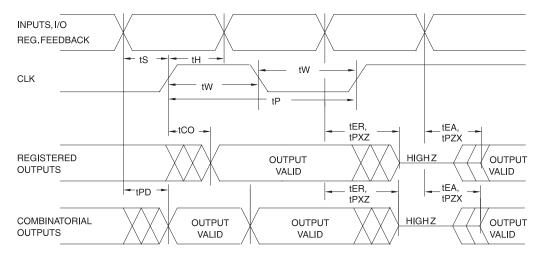
	Commercial
Operating Temperature (Case)	0°C - 70°C
V <sub>CC</sub> Power Supply	3.0V to 5.5V

#### **DC Characteristics**

Symbol	Parameter	Condition	Min	Тур	Max	Units
I <sub>IL</sub>	Input or I/O Low Leakage Current	$0 \le V_{IN} \le V_{IL}(MAX)$			-10	μΑ
I <sub>IH</sub>	Input or I/O High Leakage Current	$1.8 \le V_{IN} \le V_{CC}$			10	μΑ
I <sub>CC1</sub> <sup>(1)</sup>	Power Supply Current	15 MHz, $V_{CC} = MAX$ , $V_{IN} = 0$ , $V_{CC}$ , Outputs Open			55	mA
I <sub>PD</sub> <sup>(1)</sup>	Power Supply Current, Power Down Mode	$V_{CC} = MAX,$ $V_{IN} = 0, V_{CC}$		0.1	5	μΑ
I <sub>OS</sub>	Output Short Circuit Current	V <sub>OUT</sub> = 0.5V; V <sub>CC</sub> = 3V; T <sub>A</sub> = 25°C			-150	mA
$V_{IL}$	Input Low Voltage	MIN < V <sub>CC</sub> < MAX	-0.5		0.8	V
V <sub>IH</sub>	Input High Voltage		2.0		V <sub>CC</sub> + 1	V
V <sub>OL</sub>	Output Low Voltage	$V_{CC} = MIN$ ; All Outputs $I_{OL} = 8 \text{ mA}$			0.5	V
V <sub>OH</sub>	Output High Voltage	V <sub>CC</sub> = MIN I <sub>OL</sub> = -500 mA	2.4			V
I <sub>OL</sub>	Output Low Current	V <sub>CC</sub> = MIN	8			mA
I <sub>OH</sub>	Output High Current	V <sub>CC</sub> = MIN	-4			mA

Note: 1. All  $I_{CC}$  parameters measured with outputs open.

#### **AC Waveforms**<sup>(1)</sup>



Note: 1. Timing measurement reference is 1.5V. Input AC driving levels are 0.0V and 3.0V, unless otherwise specified.





#### **AC Characteristics**

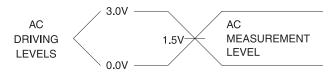
		-	-10		-15	
Symbol	Parameter	Min	Max	Min	Max	Units
t <sub>PD</sub>	Input or Feedback to Non-Registered Output	1	10	1	15	ns
t <sub>CF</sub>	Clock to Feedback		5		8	ns
t <sub>CO</sub>	Clock to Output	2	7	2	10	ns
t <sub>S</sub>	Input or Feedback Setup Time	7		12		ns
t <sub>H</sub>	Input Hold Time	0		0		ns
t <sub>P</sub>	Clock Period	12		16		ns
t <sub>W</sub>	Clock Width	6		8		ns
	External Feedback 1/(t <sub>S</sub> + t <sub>CO</sub> )		71.4		45.5	MHz
$F_{MAX}$	Internal Feedback 1/(t <sub>S</sub> + t <sub>CF</sub> )		83.3		50	MHz
	No Feedback 1/(t <sub>P</sub> )		83.3		62.5	MHz
t <sub>EA</sub>	Input to Output Enable — Product Term	3	10	3	15	ns
t <sub>ER</sub>	Input to Output Disable — Product Term	2	10	2	15	ns
t <sub>PZX</sub>	OE pin to Output Enable	2	8	2	15	ns
t <sub>PXZ</sub>	OE pin to Output Disable	1.5	8	1.5	15	ns

#### Power Down AC Characteristics (1)(2)(3)

		_	-10		15	
Symbol	Parameter	Min	Max	Min	Max	Units
t <sub>IVDH</sub>	Valid Input Before PD High	10		15		ns
t <sub>GVDH</sub>	Valid OE Before PD High	0		0		ns
t <sub>CVDH</sub>	Valid Clock Before PD High	0		0		ns
t <sub>DHIX</sub>	Input Don't Care After PD High		10		15	ns
t <sub>DHGX</sub>	OE Don't Care After PD High		10		15	ns
t <sub>DHCX</sub>	Clock Don't Care After PD High		10		15	ns
t <sub>DLIV</sub>	PD Low to Valid Input		10		15	ns
t <sub>DLGV</sub>	PD Low to Valid OE		25		30	ns
t <sub>DLCV</sub>	PD Low to Valid Clock		25		30	ns
t <sub>DLOV</sub>	PD Low to Valid Output		30		35	ns

- Notes: 1. Output data is latched and held.
  - 2. HI-Z outputs remain HI-Z.
  - 3. Clock and input transitions are ignored.

# Input Test Waveforms and Measurement Levels:



 $t_R$ ,  $t_F < 1.5$ ns (10% to 90%)

# Output Test Loads: Commercial

Note:

Similar devices are tested with slightly different loads. These load differences may affect output signals' delay and slew rate. Atmel devices are tested with sufficient margins to meet compatible devices.

#### Pin Capacitance

 $(f = 1 \text{ MHz}, T = 25^{\circ}\text{C})^{(1)}$ 

	Тур	Max	Units	Conditions
C <sub>IN</sub>	5	8	pF	V <sub>IN</sub> = 0V
C <sub>OUT</sub>	6	8	pF	V <sub>OUT</sub> = 0V

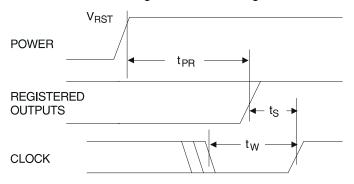
Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.

#### **Power Up Reset**

The ATF16LV8C's registers are designed to reset during power up. At a point delayed slightly from  $V_{CC}$  crossing  $V_{RST}$ , all registers will be reset to the low state. As a result, the registered output state will always be high on power-up.

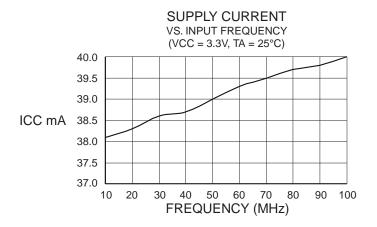
This feature is critical for state machine initialization. However, due to the asynchronous nature of reset and the uncertainty of how  $V_{CC}$  actually rises in the system, the following conditions are required:

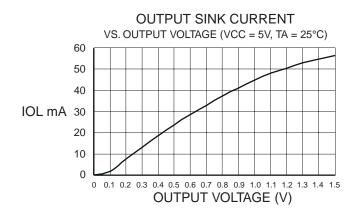
- The V<sub>CC</sub> rise must be monotonic from below 0.7 volts.
- 2. The signals from which the clock is derived must remain stable during  $T_{\text{PR}}$ .
- 3. After T<sub>PR</sub>, all input and feedback setup times must be met before driving the clock term high.

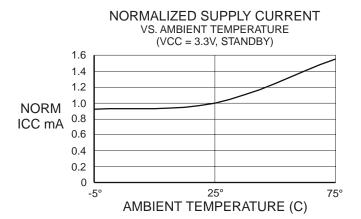


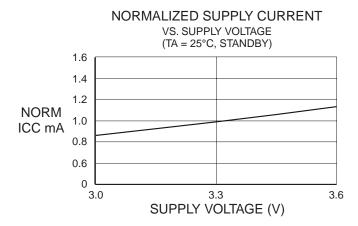
Parameter	Description	Тур	Max	Units
T <sub>PR</sub>	Power-Up Reset Time	600	1,000	ns
V <sub>RST</sub>	Power-Up Reset Voltage	2.5	3.0	V

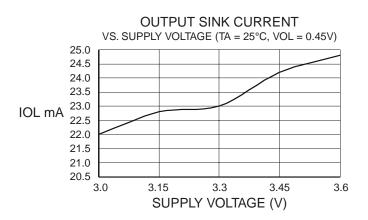


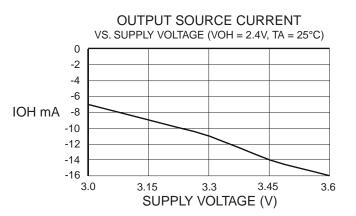




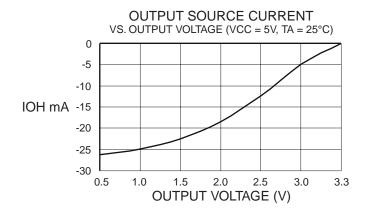


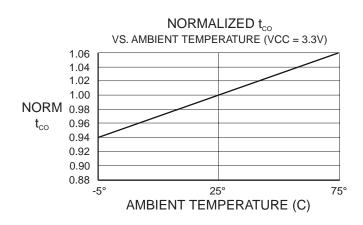


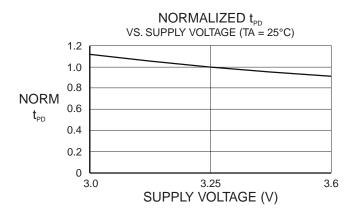


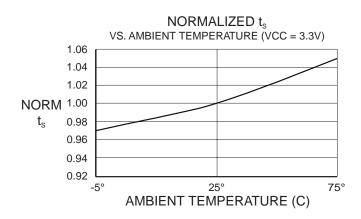


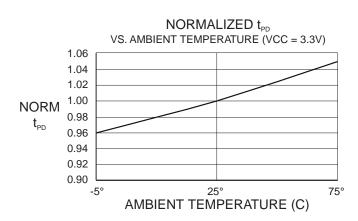
### ATF16LV8C

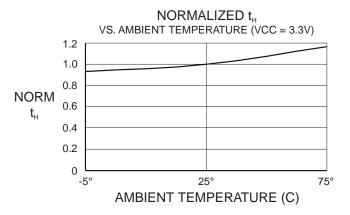






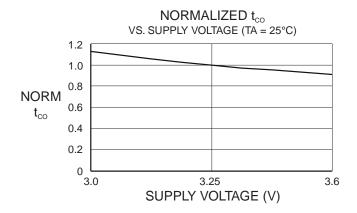


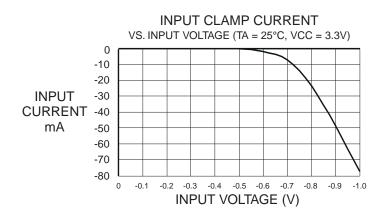


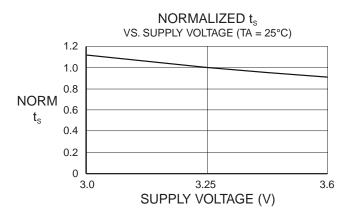


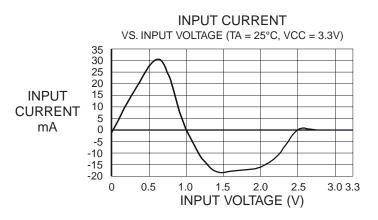


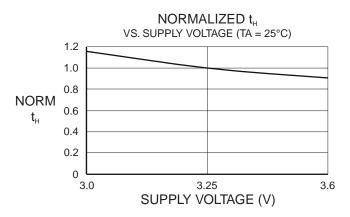












## **Ordering Information**

t <sub>PD</sub> (ns)	t <sub>s</sub> (ns)	t <sub>co</sub> (ns)	Ordering Code	Package	Operation Range
10	7	7	ATF16LV8C-10JC	20J	Commercial
			ATF16LV8C-10PC	20P3	(0°C to 70°C)
			ATF16LV8C-10SC	20S	
			ATF16LV8C-10XC	20X	
15	12	10	ATF16LV8C-15JC	20J	Commercial
			ATF16LV8C-15PC	20P3	(0°C to 70°C)
			ATF16LV8C-15SC	20S	
			ATF16LV8C-15XC	20X	
10	7	7	ATF16LV8C-10JI	20J	Industrial
			ATF16LV8C-10PI	20P3	(0°C to 85°C)
			ATF16LV8C-10SI	20S	
			ATF16LV8C-10XI	20X	
15	12	10	ATF16LV8C-15JI	20J	Industrial
			ATF16LV8C-15PI	20P3	(0°C to 85°C)
			ATF16LV8C-15SI	20\$	
			ATF16LV8C-15XI	20X	

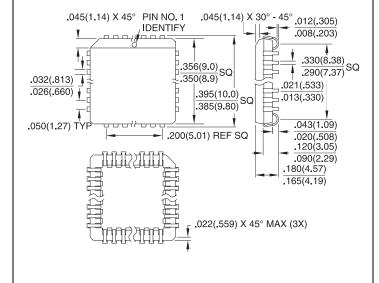
	Package Type		
20J	20J 20-Lead, Plastic J-Leaded Chip Carrier (PLCC)		
20P3	20-Lead, 0.300" Wide, Plastic Dual Inline Package (PDIP)		
20S	20S 20-Lead, 0.300" Wide, Plastic Gull Wing Small Outline (SOIC)		
20X	20-Lead, 4.4 mm Wide, Plastic Thin Shrink Small Outline (TSSOP)		





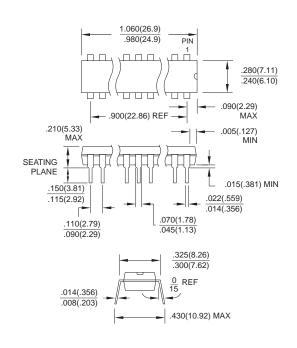
#### **Packaging Information**

**20J**, 20-Lead, Plastic J-Leaded Chip Carrier (PLCC) Dimensions in Inches and (Millimeters)
JEDEC STANDARD MS-018 AA



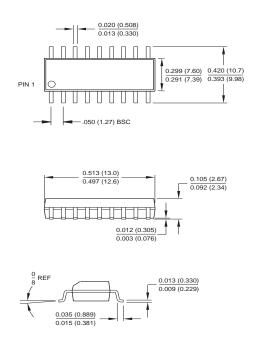
**20P3**, 20-Lead, 0.300" Wide, Plastic Dual Inline Package (PDIP)

Dimensions in Inches and (Millimeters) JEDEC STANDARD MS-001 AD



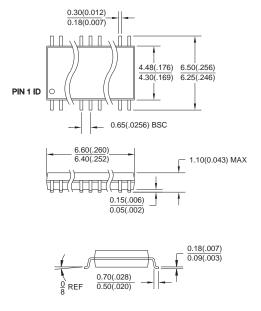
**20S**, 20-Lead, 0.300" Wide, Plastic Gull Wing Small Outline (SOIC)

Dimensions in Inches and (Millimeters)



**20X**, 20-Lead, 4.4 mm Wide, Plastic Thin Shrink Small Outline (TSSOP)

Dimensions in Millimeters and (Inches)\*



\*Controlling dimension: millimeters.